



Semiconductor Test Equipment List

Category	Manufacturer and Model	Quantity	Package Types	Contact Sites	Temperature Range (°C)	
Test Handler	MCT 5100	9	SOIC (8-20L); QSOP (16-30L); TSSOP (8-28L, 173 mils); WIDE-TSSOP (28L); WIDE-TSSOP (56L); MSOP (8L); MLP, DFN, QFN (3×3.3mm, 4×8.25mm, 4×6mm, 4×4mm, 5×6mm, 6.25×7.25mm)	Dual	25 to 125	
	MCT 3608	6	PDIP (8-28L)	Single	25 to 125	
	MCT 4610	2	TO-252 (DPAK); TO-263 (DDPAK); PLCC (20L); WSOIC	Single	-40 to 125	
	WTS 3900		3	SOIC; QSOP; DDPAK; TO-220; WIDE-SOIC	Single	25 to 125
			1	TO-263 (DDPAK, 5-7L); TO-220 (3-7L); SPAK (7L)	Single	25 to 125
			1	WIDE-SOIC (16-24L)	Single	25 to 125
	Sessco		1	WIDE-SOIC (16-24L)	Single	25 to 125
			1	TO-263 (DDPAK, 5-7L); TO-220 (3-7L)	Single	25 to 125
	Symtek 550	2	SOIC (8-16L); QSOP (16L)	Single	-40 to 125	
	Exatron 3000	1	SOT-223	Single	Room Temp	
	Aetrium 5050 DTS	1	QSOP (16L); SOIC (8L)	Single	Room Temp	
	Rasco SO1000		3	MSOP (8-10L)	Quad	-40 to 175
			1	QFN (3×3mm, 4×4mm)		
	Rasco SO2000	1	QSOP (16L); SOIC (8L)	Quad	-40 to 175	
Sillner IPS-432	1	SOT23 (Test and Taping)	Dual	Room Temp		
MCT FFH	1	QFN, DFN (2×2mm, 4×5mm, 10×12mm)	Multi	Room Temp		
Wafer Sort / Prober	Electroglas EG2001	4	4-6" wafers; MLP; DFN; QFN; SFN; CSP	Multi	25 to 125	
	Electroglas EG3000	1	4-8" wafers; MLP; DFN; QFN (Manual)	Multi	Room Temp	
	Electroglas EG4080	4	4-8" wafers; MLP; DFN; QFN; CSP	Multi	25 to 125	
	Electroglas EG4200	1	4-8" wafers; MLP; DFN; QFN; CSP	Multi	-55 to 200	
Tape and Reel	ISMECA NX32W	1	CSP (1×1mm, 1×1.5mm); Bump Die			
	ST 585	2	SOIC (8-20L); TSSOP (8-28L); QSOP (16-30L); MSOP (8-10L); W-SOIC (18-28L)			
	SV 520	1	SOIC (8-20L); QSOP (16-30L)			
	ST 60	2	SOIC (8-20L); TSSOP (8-28L); QSOP (16-30L); MSOP (8-10L); W-SOIC (18-28L); TO-263 (DDPAK); TO-220 (3-7L)			
	SV 520	1	Any packages; MLP; QFN; DFN (manual)			
	ST 485	1	Any packages; MLP; QFN; DFN (manual)			
Tester	TMT ASL 1000	18				
	TMT ASL 3000	1				